

1. A structure comprising a first conductor layer, a second conductor layer, a third conductor layer, a first dielectric material layer, a second dielectric material layer and a resistor layer, wherein:

said resistor layer is sandwiched by said first conductor layer and said second conductor layer;

said second dielectric material layer is sandwiched by said third conductor layer and said second dielectric material layer; and

2. A structure according to claim 1, wherein said first conductor layer is a first ground layer, said second conductor layer is a second ground layer and said third conductor layer is a power source layer.

3. A circuit board comprising a first conductor layer, a second conductor layer, a resistor and a dielectric material layer, wherein:

said resistor layer and said dielectric material layer are disposed between said first conductor layer and said second conductor layer; and

said resistor layer is disposed on a peripheral portion of said first conductor layer.

4. A circuit board according to Claim 3, wherein said resistor layer reduces a potential fluctuation caused at least in said first conductor layer.

5. A circuit board according to Claim 3, wherein said first conductor layer or said second conductor layer is divided.

6. A circuit board comprising a first conductor layer, a second conductor layer, a first resistor, a second resistor and a dielectric material layer, wherein:

said first resistor, said second resistor and said dielectric material layer are disposed between said first conductor layer and said second conductor layer;

said dielectric material layer is disposed between said first resistor and said second resistor;

said first resistor is disposed on a peripheral portion of said first conductor layer; and

said second resistor is disposed on a peripheral portion of said second conductor layer.

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7. A circuit board according to Claim 6, wherein said first resistor and said second resistor reduce potential fluctuations caused in said first conductor layer and said second conductor layer.

8. A circuit board according to Claim 6, wherein said first conductor layer or said second conductor layer is divided.

9. A circuit board according to Claim 6, wherein a shape of said first resistor is the same as a shape of said second resistor.

10. A circuit board comprising a ground layer, a power source layer, a first resistor, a second resistor and a dielectric material layer, wherein:

said first resistor, said second resistor and said dielectric material layer are disposed between said ground layer and said power source layer;

said dielectric material layer is disposed between said first resistor and said second resistor;

said first resistor is disposed on a peripheral portion of said ground layer; and

said second resistor is disposed on a peripheral portion of said power source layer.

11. A circuit board according to claim 10, wherein a shape of said first resistor is the same as a shape of said second resistor.

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12. A circuit board comprising a first conductor layer, a second conductor layer, a first resistor, a second resistor and a dielectric material layer, wherein:

said first resistor is disposed on a peripheral portion of said first conductor layer;

said second resistor is disposed on a peripheral portion of said second conductor layer; and

said dielectric material layer is disposed between said first resistor and said second resistor.

13. A circuit board according to Claim 12, wherein a shape of said first resistor is the same as a shape of said second resistor.

14. An electronic apparatus having electronic components provided on said structure according to Claim 1.

15. An electronic apparatus having electronic components provided on said circuit board according to Claim 3.

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